



Product Change Notification / NTDO-24ZJOF507

Date:

01-Aug-2023

Product Category:

8-bit Microcontrollers

PCN Type:

Manufacturing Change

Notification Subject:

CCB 6422 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire as new wire material for selected PIC16F153xx, PIC16F183xx, PIC16F184xx, PIC16LF153xx, PIC16LF183xx, PIC16LF184xx, PIC18F04Q4xx, PIC18F05Q4xx and PIC18F06Q4xx device families available in 14L and 8L SOIC (3.90mm) package.

Affected CPNs:

[NTDO-24ZJOF507_Affected_CPN_08012023.pdf](#)
[NTDO-24ZJOF507_Affected_CPN_08012023.csv](#)

Notification Text:

PCN Status:Initial Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of palladium coated copper with gold flash (CuPdAu) bond wire as new wire material for selected PIC16F153xx, PIC16F183xx, PIC16F184xx, PIC16LF153xx, PIC16LF183xx, PIC16LF184xx, PIC18F04Q4xx, PIC18F05Q4xx and PIC18F06Q4xx device families available in 14L and 8L SOIC (3.90mm) package.

Pre and Post Change Summary:

	Pre Change	Post Change	
Assembly Site	Microchip Technology Thailand (Branch) / (MMT)	Microchip Technology Thailand (Branch) / (MMT)	
Wire Material	Au	CuPdAu	
Die Attach Material	8390A	8390A	
Molding Compound Material	G600V	G600V	
Lead-Frame Material	CDA194	CDA194	
Lead-Frame Paddle Size	95x155 mils 104x150 mils	95x155 mils 104x150 mils	95x130 mils
DAP Surface Prep	Ag Spot Bare Cu	Bare Cu	

Impacts to Data Sheet:

None

Change ImpactNone

Reason for Change: To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) bond wire.

Change Implementation Status: In Progress

Estimated Qualification Completion Date:September 2023

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

Qual Report Availability									X
Final PCN Issue Date									X

Method to Identify Change:Traceability code

Qualification Plan:Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History:August 1, 2022: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_NTDO-24ZJOF507_Qual_Plan.pdf](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.